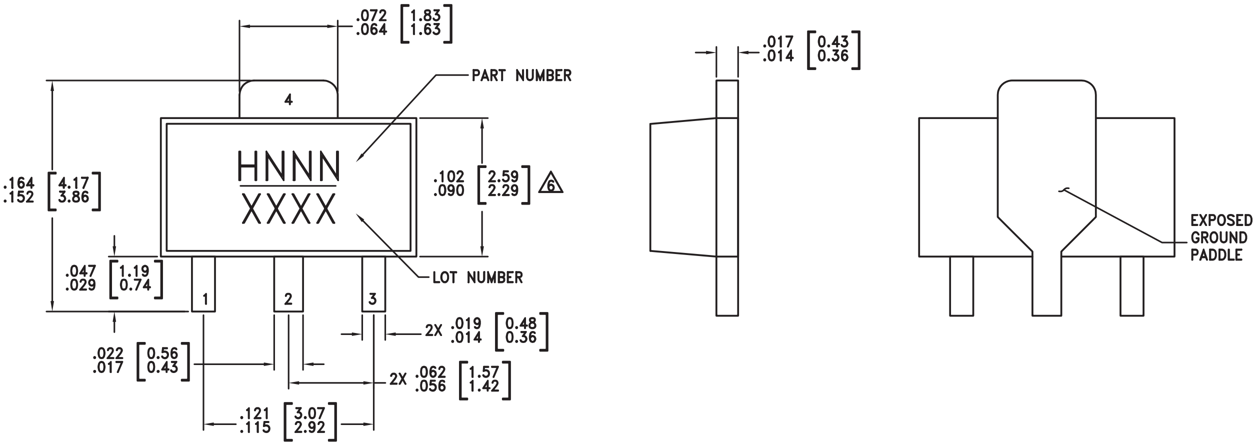
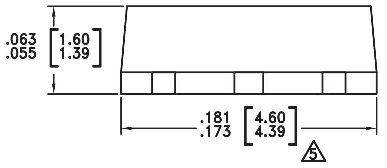
v01.0109

ST89 (E) – 4 LEAD PLASTIC SOT89 PACKAGE

ST89 (E) Package Outline Drawing





NOTES:
1. PACKAGE BODY MATERIAL:
MOLDING COMPOUND MP-180S OR EQUIVALENT.
2. LEAD MATERIAL: Cu w/ Ag SPOT PLATING.
3. LEAD PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
5 DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
6 DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
ST89	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HNNN XXXX
ST89E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HNNN XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN

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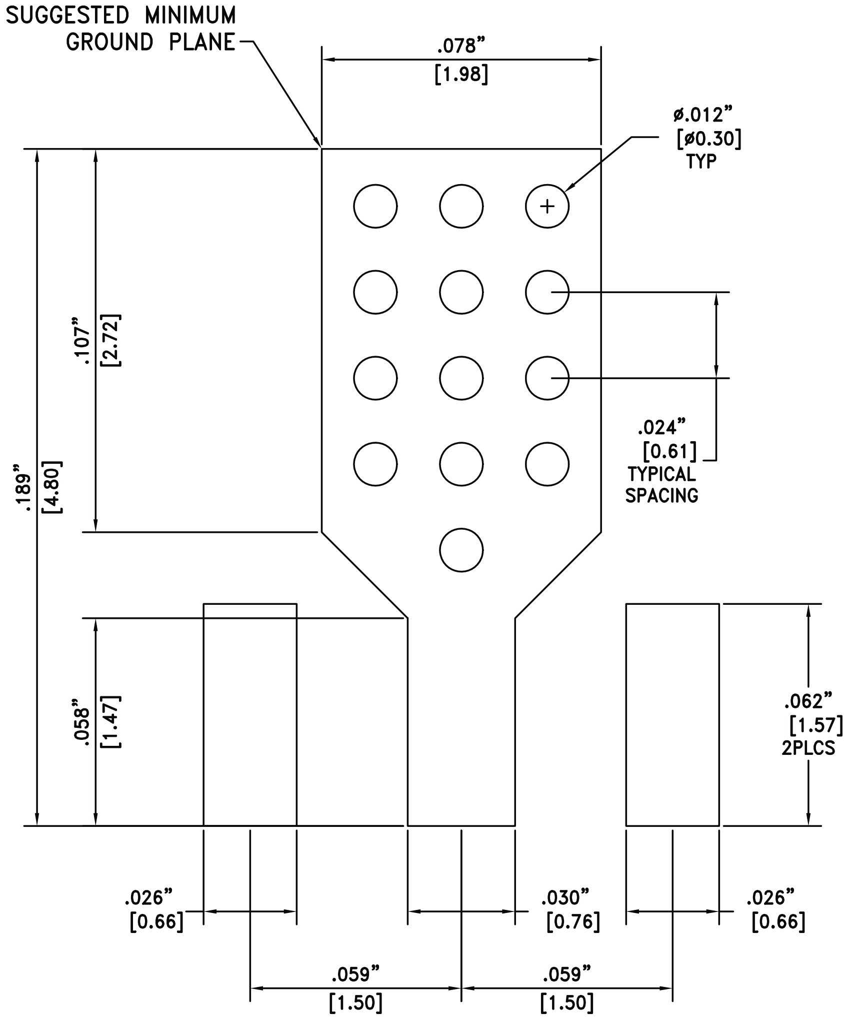
Suggested ST89 (E) PCB Land Pattern



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.